
Supporting Information

Enhanced Electrical Properties of Lithography-Free Fabricated MoS₂ Field Effect Transistors with Chromium Contacts

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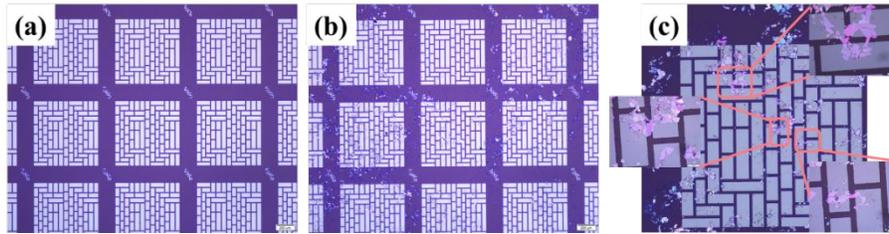


Figure S1. The optical microscope image of maze-like source/drain electrodes. (a) before and (b) after MoS₂ crystals mechanically exfoliated and MoS₂ flakes transferred. (c) The optical microscope image of maze-like source/drain electrodes with MoS₂ flakes at higher magnification, the selected devices are marked with orange boxes. Here, the substrate is Si/SiO₂ and the metal of source/drain electrodes is 20 nm-chromium (Cr), and the space between electrodes are set to be 5 or 10 μm. The flakes are exfoliated and the probability of single channel/multiple channels being formed on the same source drain electrode pair is quite high. It is noted that the multiple channels formed on the same source/drain electrode pair can result in reduced yield of final devices which should be carefully examined.

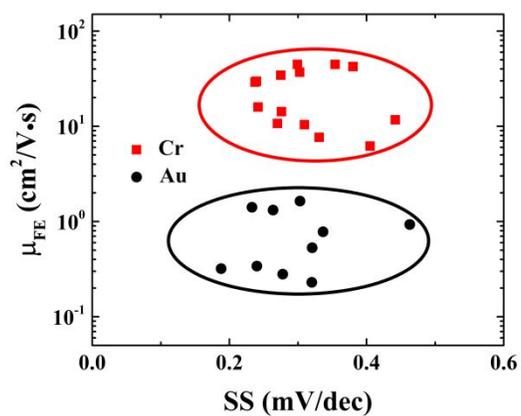


Figure S2. Statistics of Cr-MoS₂ FETs and Au-MoS₂ FETs in terms μ_{FE} and SS_{min} , demonstrating a beneficial trend in device performance as a result of Cr source/drain electrodes for a total of 10+ devices. The electrical parameters of multilayer MoS₂ FETs are extracted at $V_{DS} = 50$ mV.

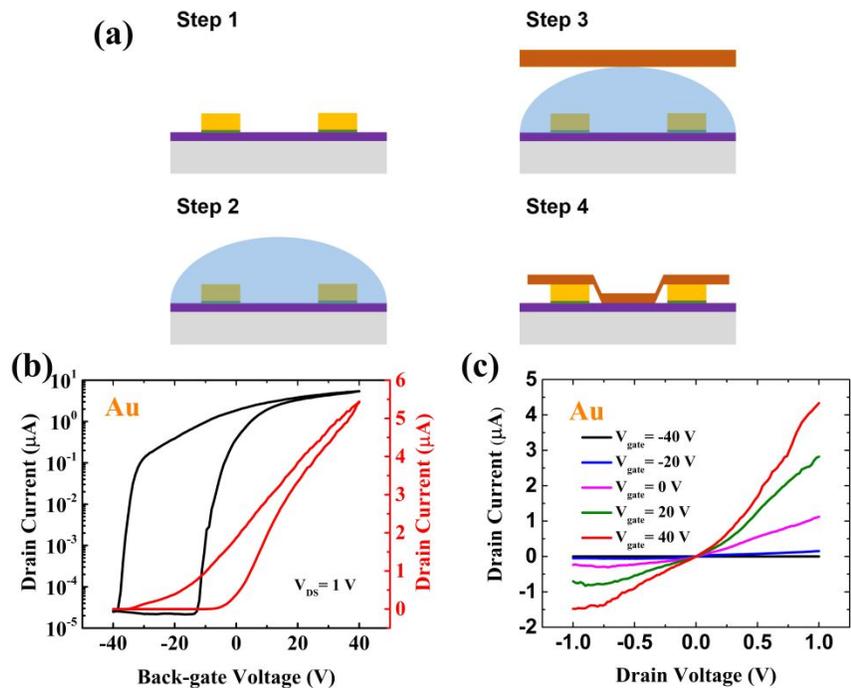


Figure S3. Fabrication of Au-MoS₂ FETs using liquid assisted exfoliation method and electrical performance of a typical Au-MoS₂ FET. (a) The control experiment flow of using solution to create more intimate contact between multilayer MoS₂ and Au electrodes. Step 1, Prepare the substrate; Step 2, Drop with a drop of solution (mixture of alcohol and deionized water, the ratio is 1:1) on the substrate, then transferring the MoS₂ flake onto the moist substrate (Step 3); Step 4, Find the target multilayer MoS₂ FET. The multilayer MoS₂ FET is characterized after the solution is completely volatilized. (b) Transfer curves of Au-MoS₂ FET using solution assisted exfoliation. (c) Output curves of Au-MoS₂ FET using solution assisted exfoliation.

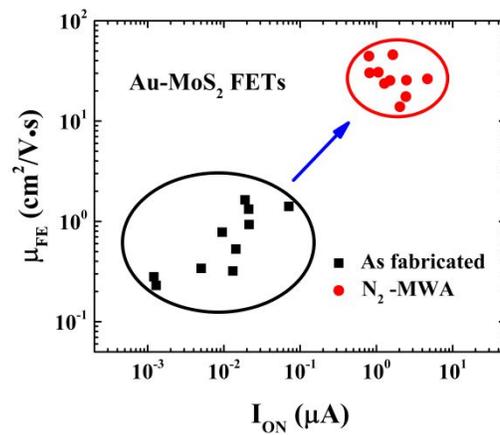


Figure S4. Statistics of Au-MoS₂ FETs before and after MWA in terms μ_{FE} and I_{ON} , demonstrating a beneficial trend in device performance as a result of MWA for a total of 10 devices. The electrical parameters of multilayer MoS₂ FETs are extracted at $V_{DS} = 50$ mV.

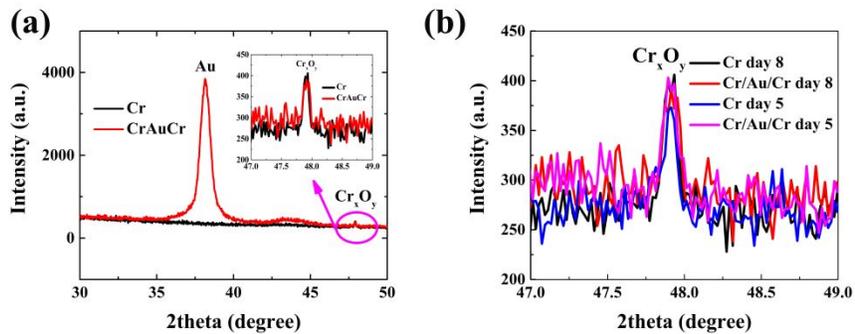


Figure S5. XRD image of Cr and Cr/Au/Cr films on the eighth day. As shown in Figure S6, the Cr_xO_y peak intensity of the two films was basically at the same level, and was consistent with the peak intensity of Cr/Au/Cr film on the fifth day. Therefore, it was inferred that Cr metal reached stable oxidation level after 8 days.

Supplementary Notes

Note 1: Extraction of intrinsic mobility and contact resistance.

Here, we used Y-function method to evaluate the electrical parameters of the fabricated multilayer MoS₂ FETs, and it has been proven that Y-function is a reliable method of extracting intrinsic mobility and contact resistance in MoS₂ FETs.¹⁻²

The Y-function method is based on the analysis of the transfer characteristics (I_{DS} - V_{GS}) in the linear region. Considering that $V_{GS}-V_{TH} \gg V_{DS}$ under strong inversion at low V_{DS} , the I_{DS} - V_{GS} equation in the linear region can be simply expressed as¹

$$I_{DS} = C_{OX} \frac{W}{L} (V_{GS} - V_{TH}) V_{DS} \left(\frac{\mu_0}{1 + \theta(V_{GS} - V_{TH})} \right) \quad (S1)$$

Where C_{OX} is the gate capacitance, W and L are the FET width and length, respectively. V_{TH} is the threshold voltage, V_{GS} and V_{DS} are the gate and drain voltages, respectively. The mobility degradation factor, $\theta = \theta_0 + \mu_0 C_{OX} \frac{W}{L} R_C$, is included to better depict the realistic device performance. μ_0 and R_C are the intrinsic mobility and contact resistance, respectively.

Assume that R_C is not V_{GS} dependent, Y-function can be expressed as

$$Y = \frac{I_{DS}}{g_m} = \left(C_{OX} \frac{W}{L} V_{DS} \mu_0 \right)^{0.5} (V_{GS} - V_{TH}) \quad (S2)$$

Where g_m is the transconductance defined as dI_{DS}/dV_{GS} . The Y-function curve can be used to extract the V_{TH} (intercept), and μ_0 (slope) of the MoS₂ FET.

Using equation (1), θ can be calculated by the known V_{TH} and μ_0 . As demonstrated by Na,² the θ_0 component can be ignored in multilayer MoS₂ FET. Then the R_C can be calculated by the known θ and μ_0 .

Reference

- (1) Chang, H. Y.; Zhu, W. N.; Akinwande, D. On the Mobility and Contact Resistance Evaluation for Transistors Based on MoS₂ or Two-Dimensional Semiconducting Atomic Crystals. *Appl. Phys. Lett.* **2014**, *104*, 113504.
- (2) Na, J.; Shin, M.; Joo, M. K.; Huh, J.; Kim, Y. J.; Choi, H. J.; Shim, J. H.; Kim, G. T. Separation of Interlayer Resistance in Multilayer MoS₂ Field-Effect Transistors. *Appl. Phys. Lett.* **2014**, *104*, 233502.